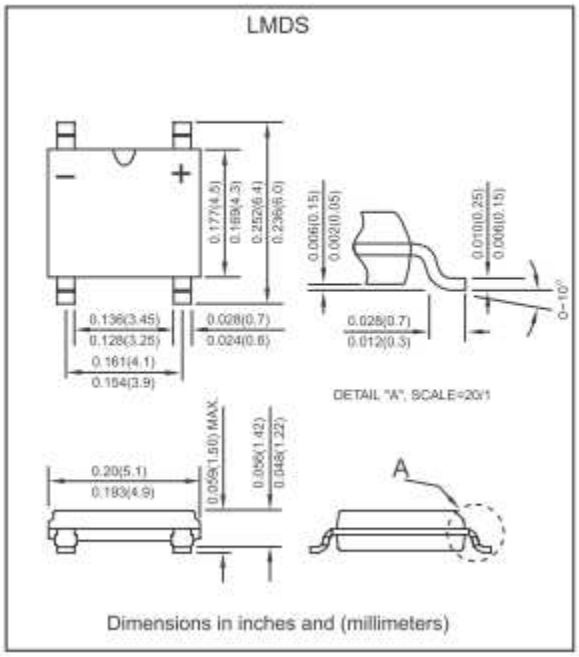
Features

- Glass passivated junction
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260℃ / 10 seconds / 0.375" (9.5mm) lead length at 5 lbs., (2.3 kg) tension
- High surge current capability
- Suffix "-H" indicates Halogen-free part, ex.ECCBRABS2-6-H.

Package outline



Mechanical Data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, LMDS
- Terminals : Solder plated, solderable per MIL-STD-202, Method 208
- Polarity : marked on body
- Mounting Position : Any
- Weight : Approximated 0.0992 gram

Maximum ratings and Electrical Characteristics (At T_A=25 ℃ unless otherwise noted)

PARAMETER	SYMBOLS	ABS2-6	ABS4-6	ABS6-6	ABS8-6	ABS10-6	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On aluminum substrate	I_O	1.0					A
Peak forward surge current 8.3 ms single half sine-wave (JEDECMethod)	I_{FSM}	30					A
Maximum instantaneous forward voltage at IF=1.0A	V_F	1.1					V
Rating for fusingt < 8.3 ms	I^2t	3.7					A2s
Maximum DC reverse current TJ=25℃ At rated DC blocking voltage TJ=125℃	I_R	5.0 500					uA
Typical thermal resistance junction to ambient Typical thermal resistance junction to lead	$R_{\theta JA}$ $R_{\theta JL}$	80 25					℃/W
Operating junction temperature range	T_J	-55 to +150					℃
Storage temperature range	T_{STG}	-55 to +150					℃

Rating and characteristic curves

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

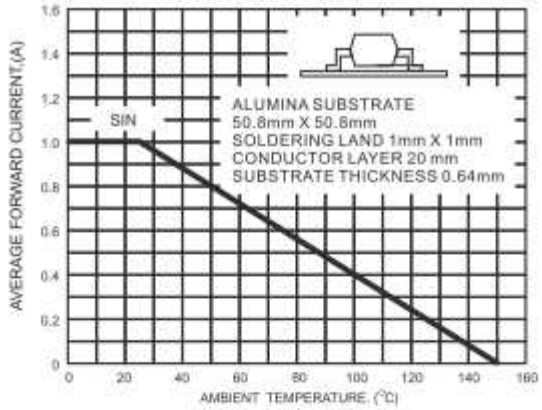


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

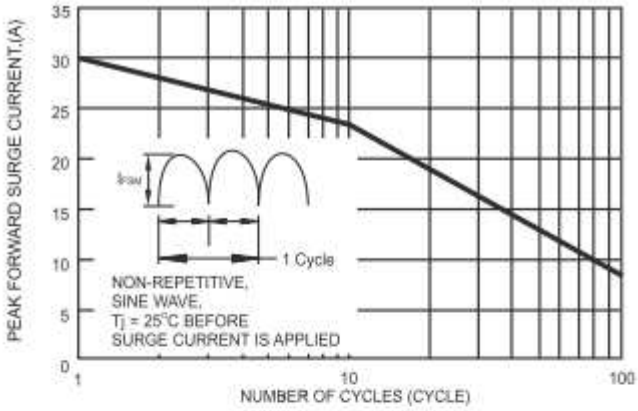


FIG.3-TYPICAL FORWARD CHARACTERISTICS

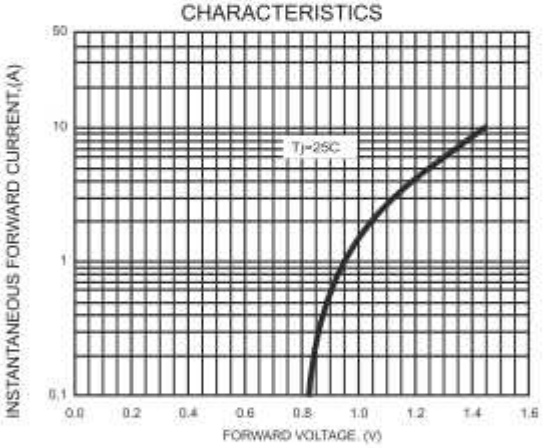


FIG.4-TYPICAL REVERSE CHARACTERISTICS

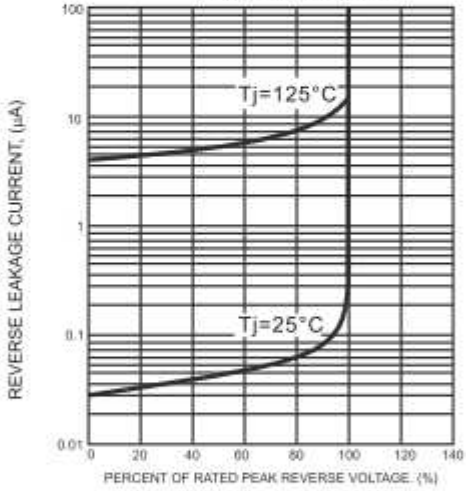
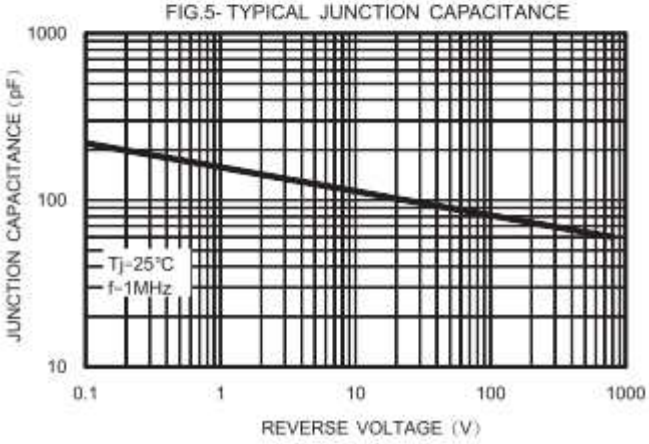
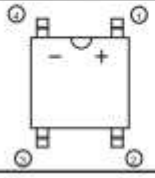
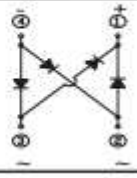


FIG.5- TYPICAL JUNCTION CAPACITANCE



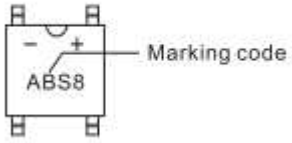
Pinning information

Simplified outline	Symbol
	

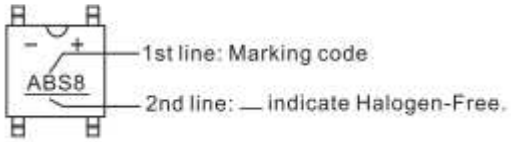
Marking

Part No	Marking
ECCBRABS2-6 / ECCBRABS2-6-H	ABS2
ECCBRABS4-6 / ECCBRABS4-6-H	ABS4
ECCBRABS6-6 / ECCBRABS6-6-H	ABS6
ECCBRABS8-6 / ECCBRABS8-6-H	ABS8
ECCBRABS10-6 / ECCBRABS10-6-H	ABS10

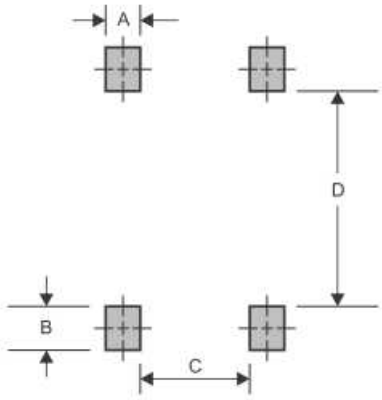
1. For Halogen Device



2. For Halogen-free Device



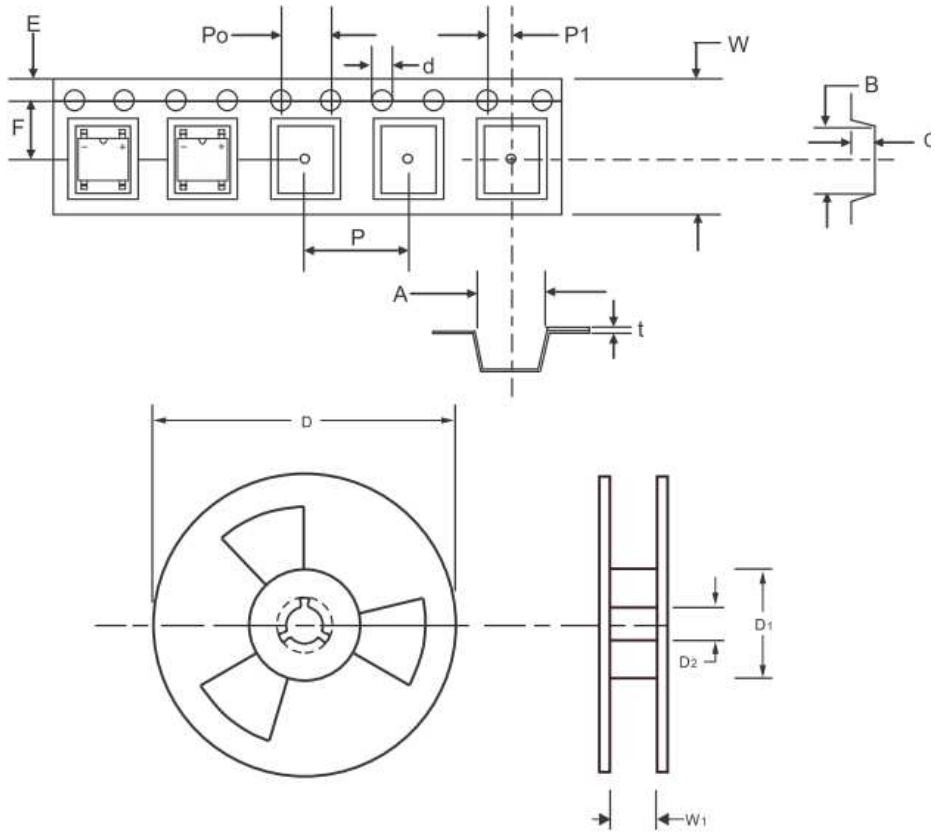
Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
LMDS	0.032 (0.80)	0.032 (0.80)	0.132 (3.35)	0.193 (4.90)

Packing information



unit:mm

Item	Symbol	Tolerance	LMDS
Carrier width	A	0.1	5.31
Carrier length	B	0.1	6.68
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D_1	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D_1	min	-
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.05	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.05	2.00
Overall tape thickness	t	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W_1	1.0	12~14.4

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
LMDS	13"	5,000	8.0	10,000	337*337*37	330	350*330*360	80,000	19.0